

# Broad band light trapping in Si ( thickness <100 μm ) by making nanoholes on micro pyramids

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### Research Objectives

Si solar cells market share upto 90%

Developing technology for Si (<100 μm) PERC and IBC solar cells

**Purpose**

- To reduce the production cost
- To enhance the efficiency (by controlling optical and electrical losses)

We control optical loss by light trapping in industrial scale

Surface texturing  
Wet etching  
Reflectance minimum ~9%

Needs to reduce surface reflections below 3%

Ref: Martin Green, Renew. Economy

### Experimental Details

**Plasma etching**

**Neutral beam etching (NBE)**

By using carbon aperture  
• UV photons are eliminated  
• Ions are neutralized

We can obtain highly collimated and accelerated beam of neutral particles.

NBE, damage free process

Ref: S. Samukawa *et al.*, Jpn. J. Appl. Phys. 40, 1997 (2001).

### Results

Maskless neutral beam etching (NBE) to make nanoholes

**Wet etching** → **Maskless NBE**

Low aspect ratio nano structures (100 nm)

Surface Reflections ~9% → Surface reflections below 4%

**Etching mechanism**

**SF<sub>6</sub>+O<sub>2</sub> gas** → Plasma → Ions, UV and Radicals → Neutralize → Low energy neutrals: Physical etching  
Radicals: Chemical etching

**Etching mechanism**

Neutrals (etchant gas) Free radicals → Adsorb → React → Gaseous products

**SF<sub>6</sub>+O<sub>2</sub> gas chemistry**

$$Si + F \rightarrow SiF_x$$

$$SiF_x + O \rightarrow SiF_xO$$

Heating at 100 to 150 °C

$$SiF_xO_x \rightarrow SiO_2(s) + SiF_4(g) \uparrow$$

(1 nm)

Self passivation layer, the interface defect density between Si and SiO<sub>2</sub> is very small

**Etch recipe: ICP=1000 watts, Stage temperature = 20°C, V<sub>pp</sub>=50 volts, Etch time = 4 min**

V<sub>pp</sub>=50 volts means neutral particles have very low energy which will participate in making nanoholes.

- SF<sub>6</sub>(65 %)/O<sub>2</sub>(35 %)
- SF<sub>6</sub>(50 %)/O<sub>2</sub>(50 %)
- SF<sub>6</sub>(35 %)/O<sub>2</sub>(65 %)

Optimized NBE recipe (SF<sub>6</sub> (35%)/O<sub>2</sub> (65%) and bias (V<sub>pp</sub>=50 V)) to generate low aspect ratio nano structures (with hole depth = 75 to 100 nm and hole diameter = 100 to 200 nm) on micro pyramids.

Surface reflections are decreased to below 4% in broad wavelength range.

### Discussion

**Reflection Spectrum**

**Wet etch**

**SF<sub>6</sub> (65%)/O<sub>2</sub> (35%)**

**SF<sub>6</sub> (50%)/O<sub>2</sub> (50%)**

**SF<sub>6</sub> (35%)/O<sub>2</sub> (65%)**

3.5%

**Si etching chemistry**

Si wafer thickness = 180 micron

Chlorine (Cl<sub>2</sub>) - Less radicals  
- Physical etching  
- Anisotropic etching

Fluorine (F) - Large number of radicals  
- Physical and chemical etching  
- Isotropic etching

$$Si(s) + 4Cl(g) \rightarrow SiCl_4(g)$$

$$Si(s) + 4F(g) \rightarrow SiF_4(g)$$

**ICP Power= 2000 Watts, V<sub>pp</sub>= 500 Volts**

1. Cl<sub>2</sub>(90%)/SF<sub>6</sub>(10 %) Etch time= 15 minutes

2. Cl<sub>2</sub>(95%)/SF<sub>6</sub>(5 %)

**Top and cross section view**

1000 nm

**Surface Reflectance %**

**Flat surface**

**Cl<sub>2</sub>(90%)/SF<sub>6</sub>(10 %) 15 min**

**Cl<sub>2</sub>(95%)/SF<sub>6</sub>(5 %) 35 min**

NB textured honeycomb structures show broad band optical light trapping with low surface reflections (5% to 1%) in the wavelength from 400 to 1040 nm.

H. Sekhar *et al.*, "Nano holes on micro pyramids; broadband optical light trapping in thin wafer based Si (<100 μm) solar cells" Proc. 16th Int. Conf. Nanotechnology, 415-418, (2016)

### Summary

- Introducing new innovative damage free (NBE) technology to trap the light in thin wafer based Si (<100 μm) solar cells.
- Nano holes with optimum etch depths (100 nm) on micro pyramids decrease surface reflections below 4% in broad wavelength range compare to their micro pyramids (9%).
- NBE applied to texture honeycomb pattern.
- Using NBE, we achieve very low surface reflections, 5% to 1% in the spectral range from 400 nm to 1040 nm.

### Reference

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